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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

[Handwritten signature]
#4 2/17/04

IN RE APPLICATION OF: : Date: 2/3/2004
CELAYA, PHILLIP et al. : Group: 2827
APPLN. NO. 09/817330 : Examiner: Thiem D. Phan
FILED: 3/26/2001 :
FOR: METHOD OF MAKING AN
INTEGRATED CIRCUIT PACKAGE

I HEREBY CERTIFY THAT THIS CORRESPONDENCE IS BEING DEPOSITED WITH
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SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
Name of Assignee

By: *[Signature]* 2/3/04
Lydia McNamara DATE

SUBMITTAL OF FORMAL DRAWINGS

Honorable Commissioner of Patents and Trademarks,
P.O. Box 1450
Alexandria, VA 22313-1450
Attn: Official Draftsman

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TECHNOLOGY CENTER

SIR:

In accordance with the requirement in PTO-948, we
are hereby submitting three (3) sheets of formal drawings
for the above-identified patent application.

The Commissioner is hereby authorized to charge any
fees to Deposit Account 501086.

Respectfully submitted,

Phillip Celaya et al.

[Signature]

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